

Data sheet Product ICK BGA 33 x 33 x 14



Heatsinks and active heatsinks for processors > Heatsinks for BGAs
33 x 33 x 14 mm, for IC design BGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	33 mm
height:	14 mm
plate thickness:	1.8 mm
length:	33 mm
thermal resistance:	15 - 4.3 K/W
dissipation loss:	4 W
surface:	black anodised

Technical Drawing

